

6231776

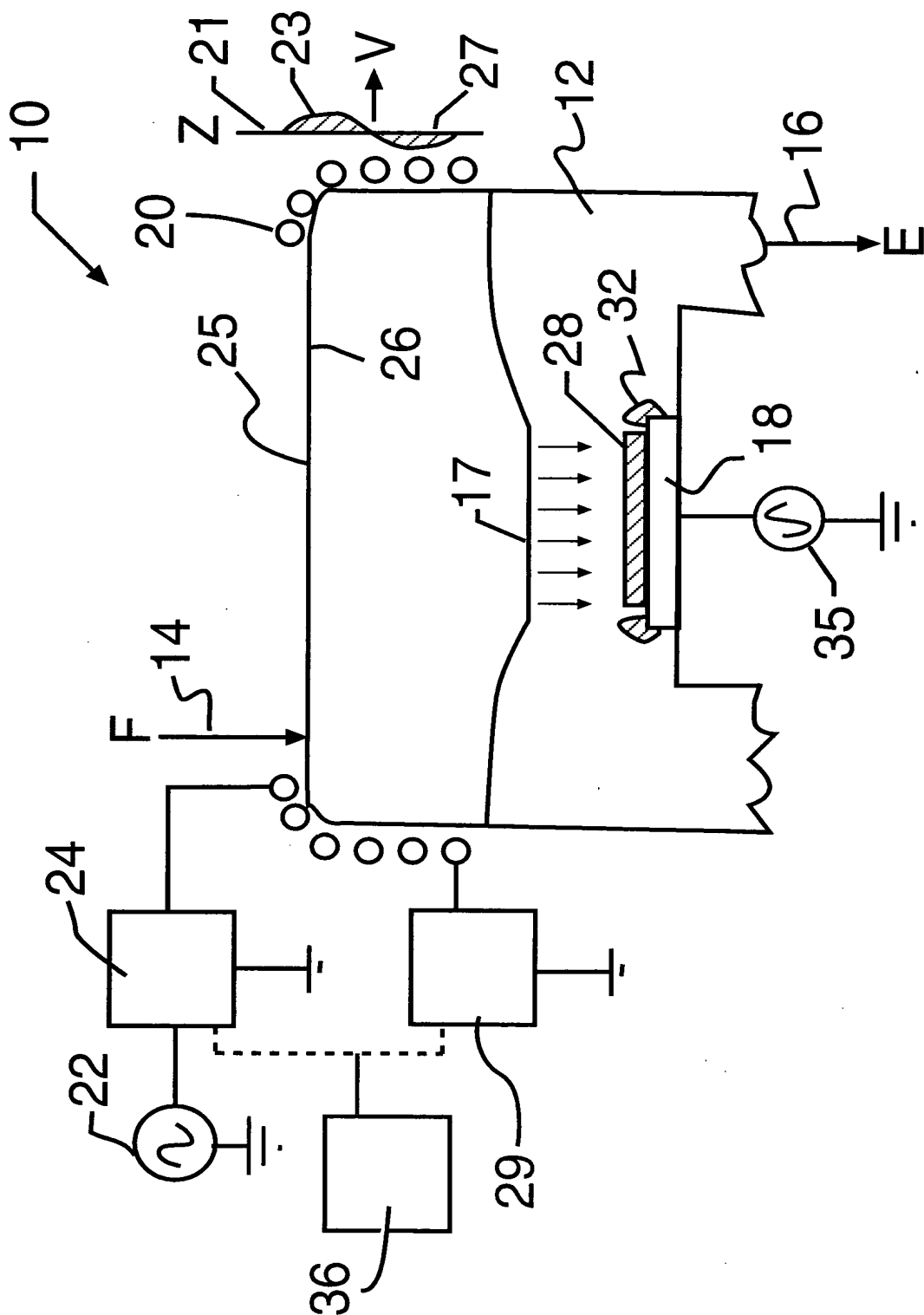


FIG. 1

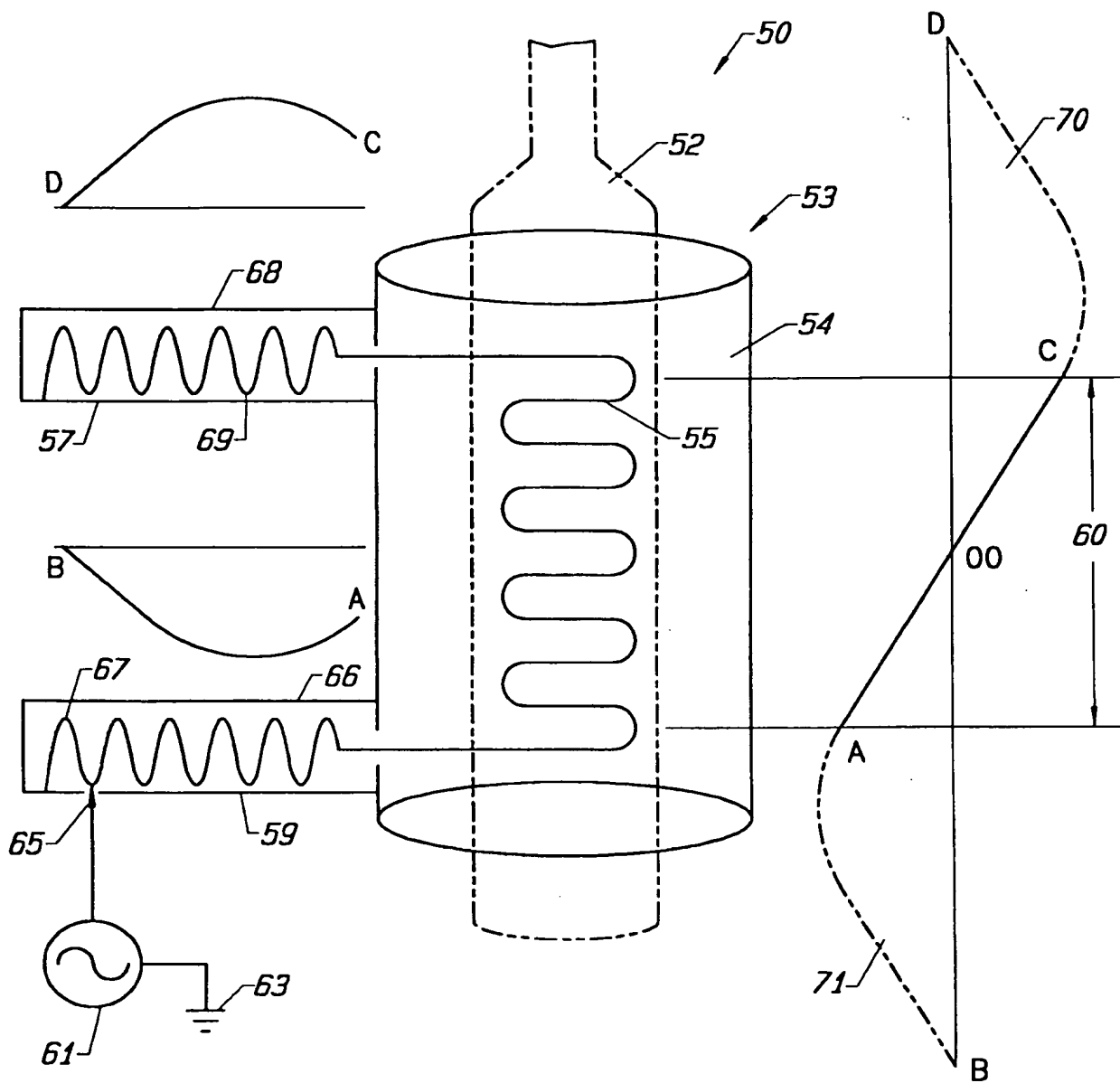


FIG. 2A

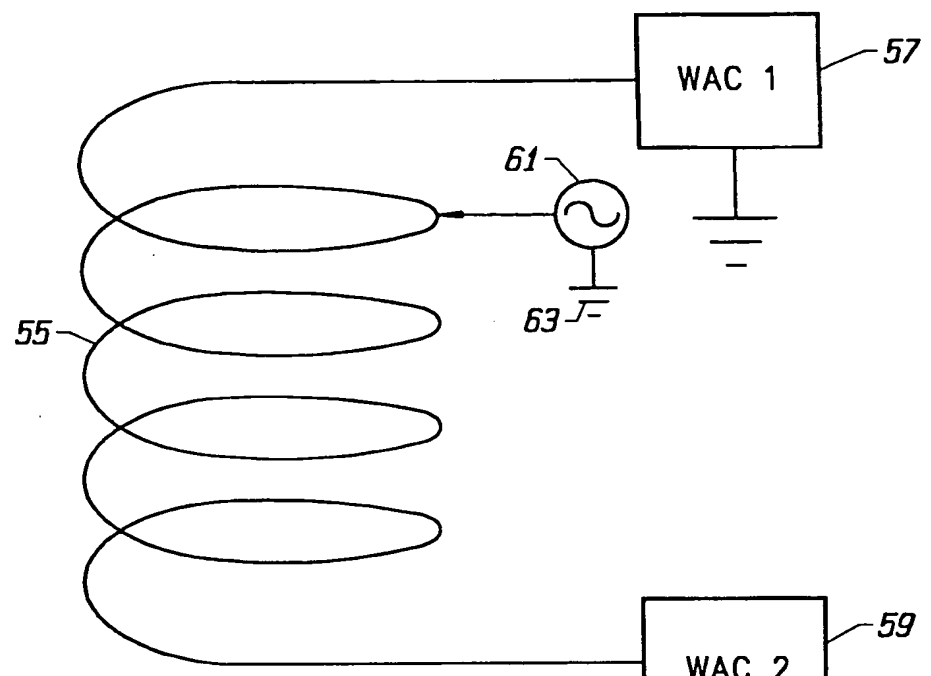


FIG. 2B

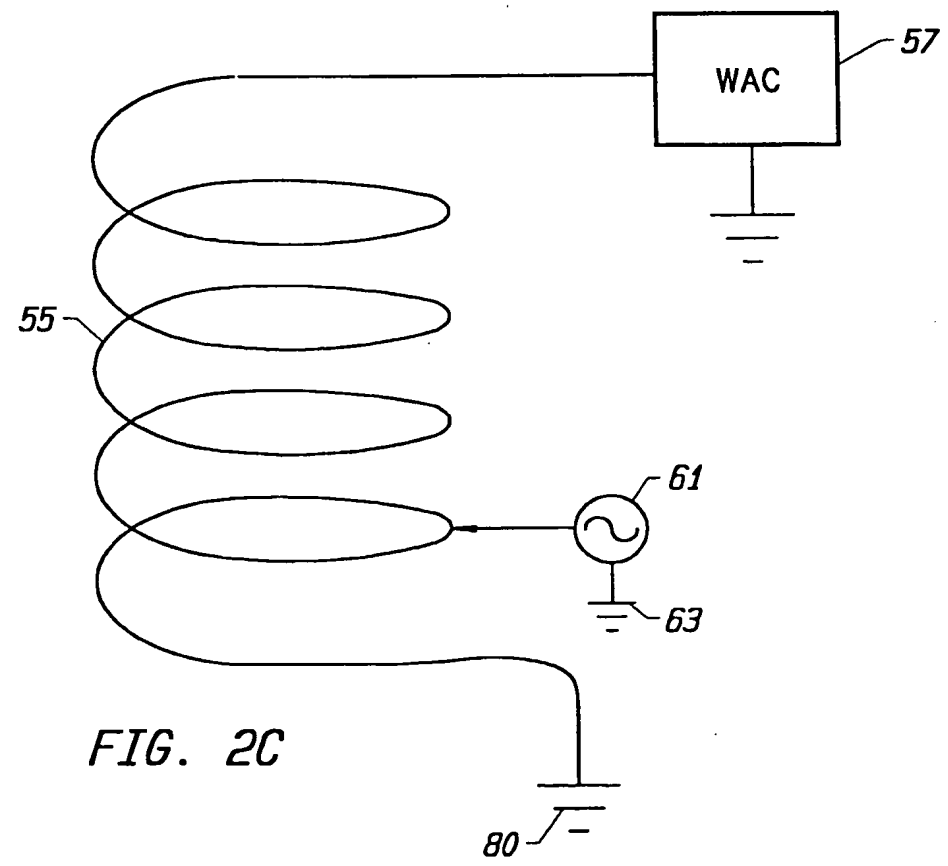


FIG. 2C

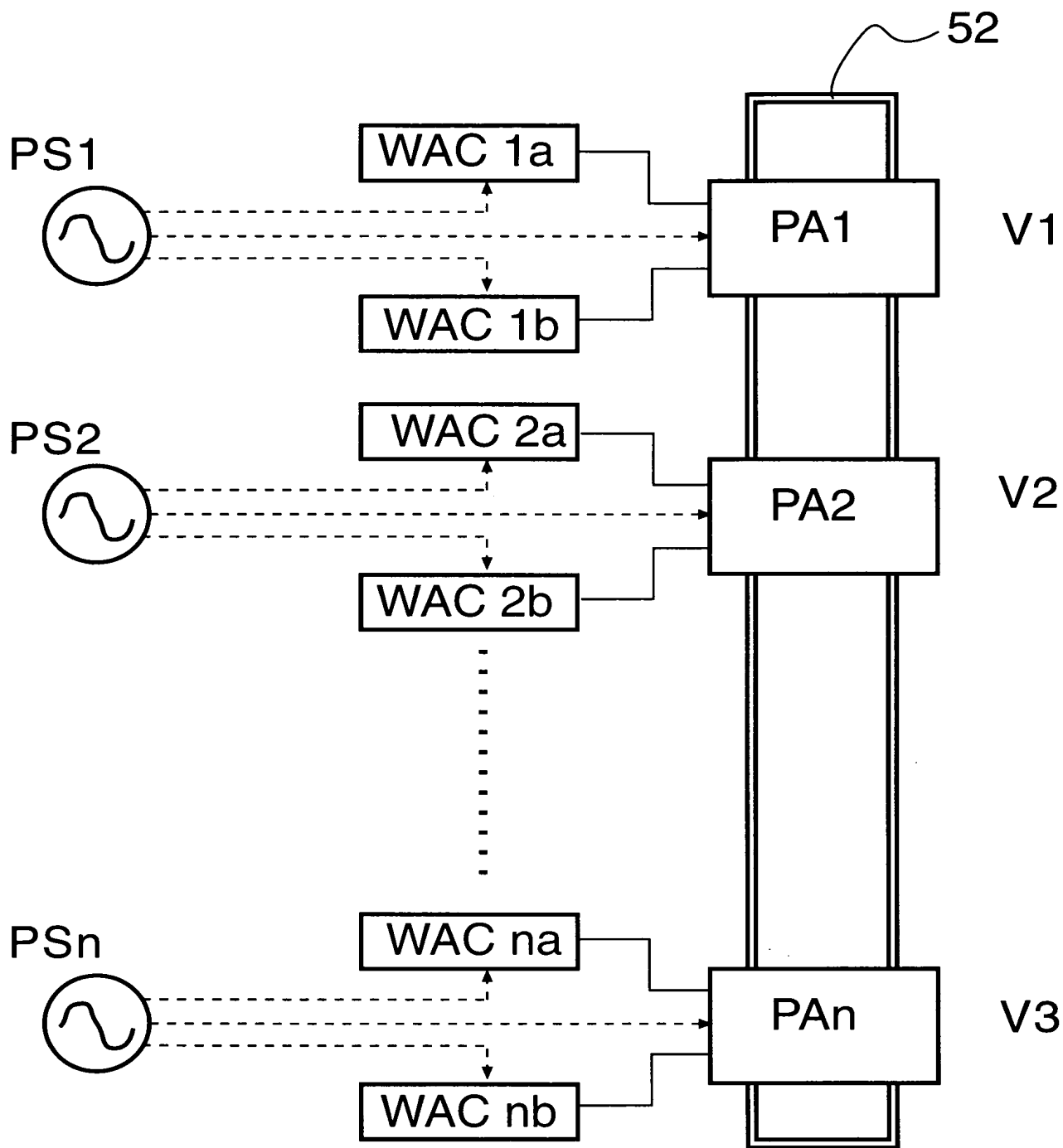
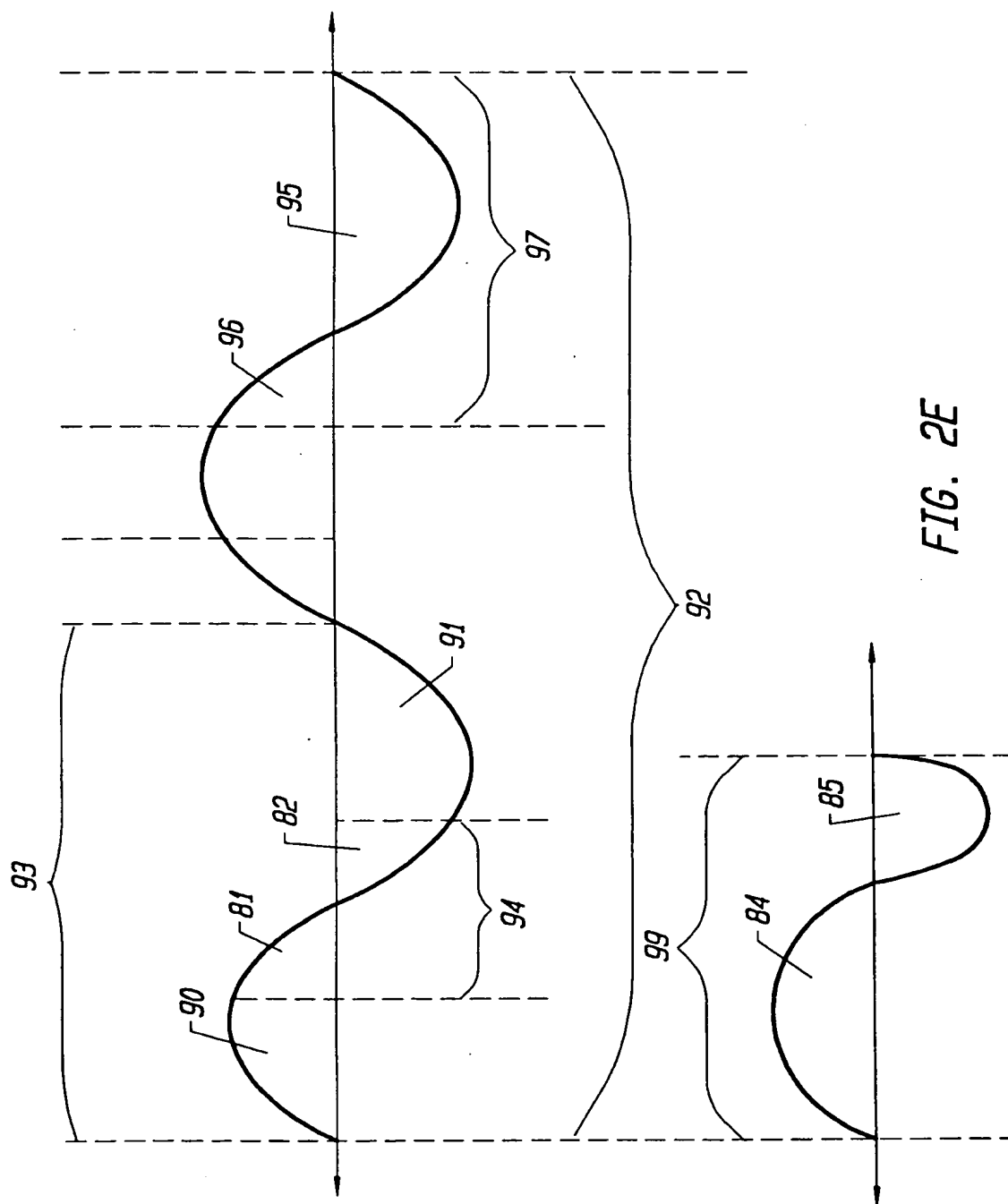


Fig. 2D

APPROVED	O.G. FIG.	
BY	CLASS	SUBCLASS
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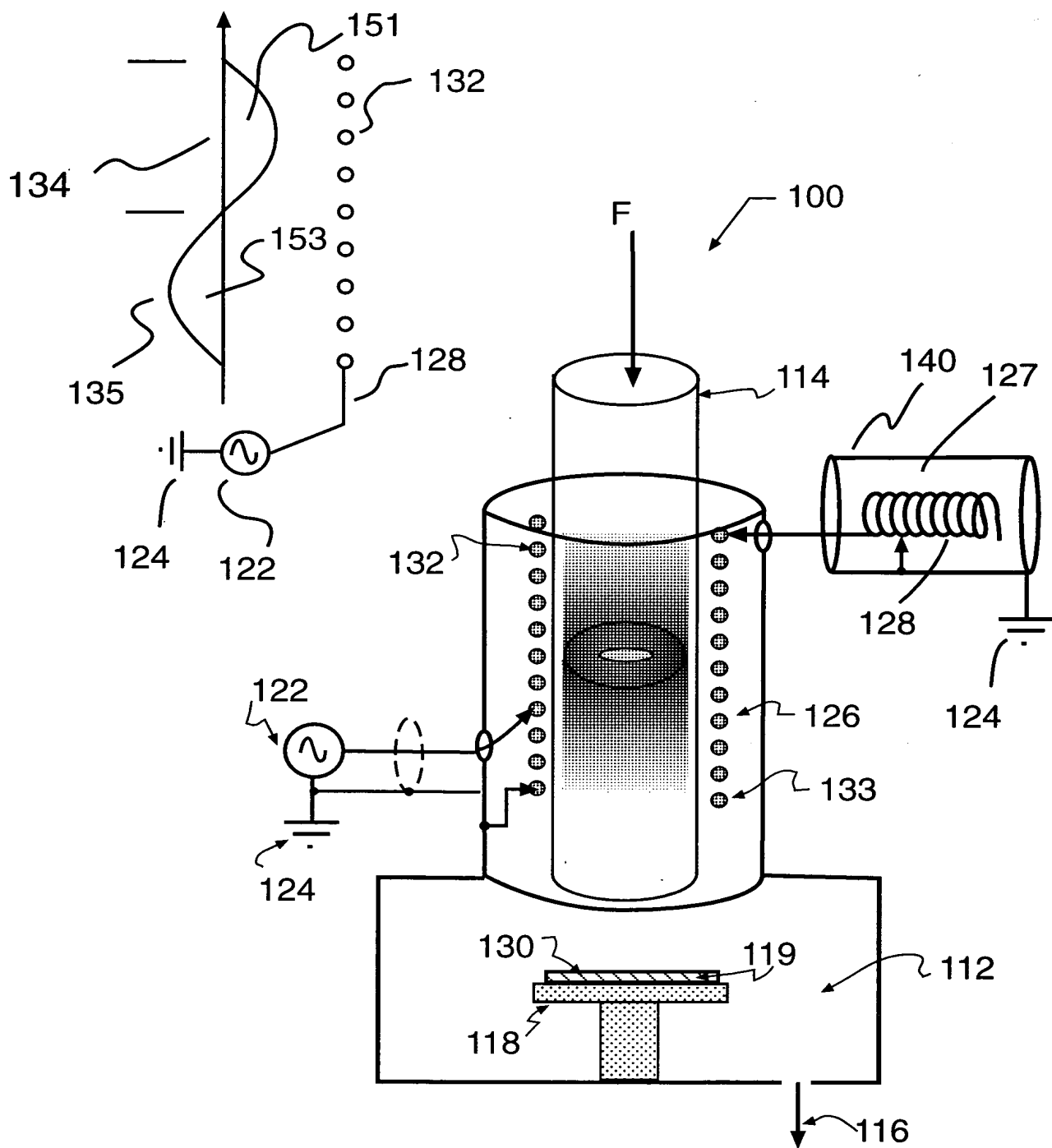


Fig. 3

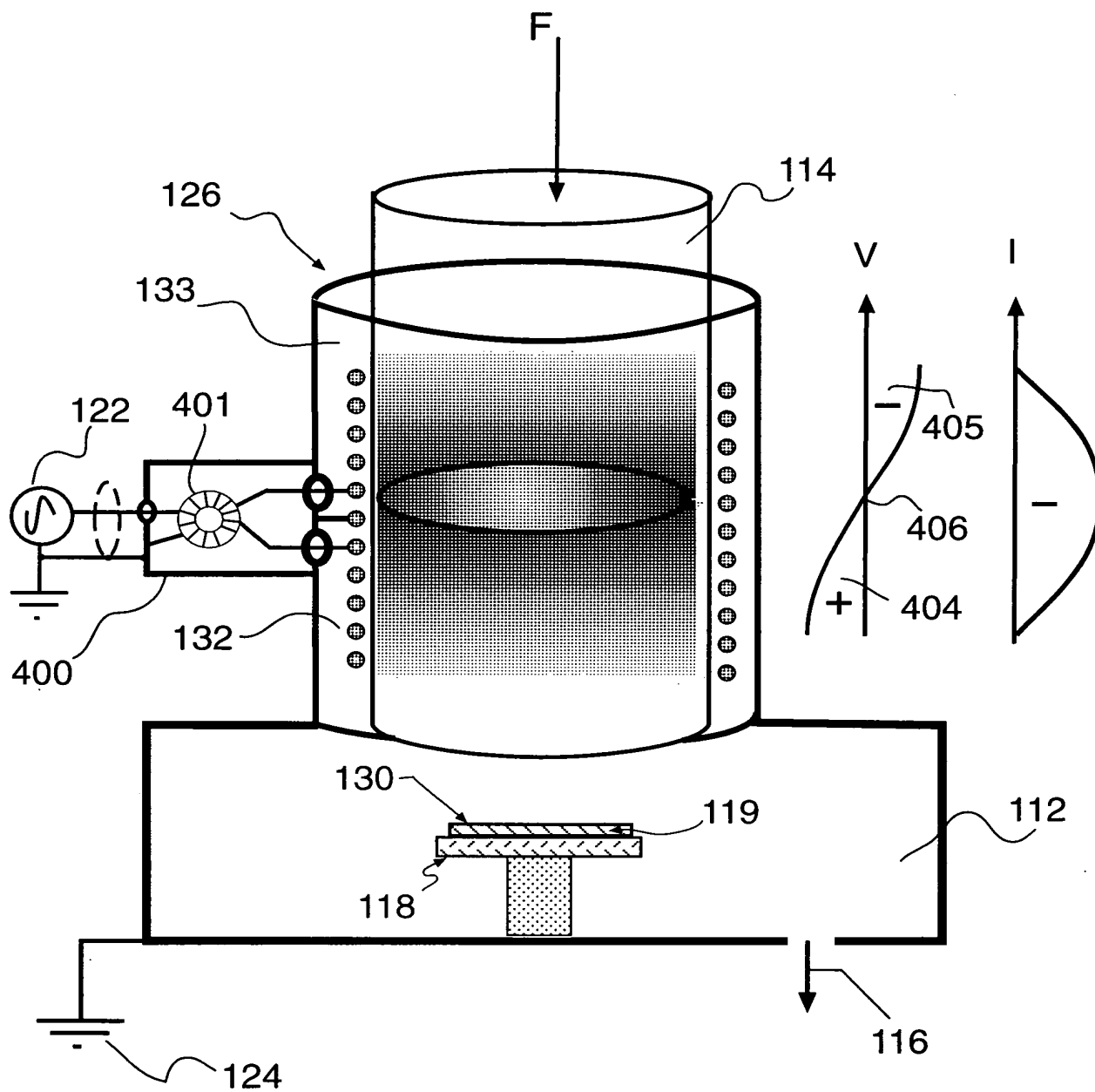


Fig. 4

APPROVED	O.G. FIG.	
BY	CLASS	SUBCLASS
DRAFTSMAN		

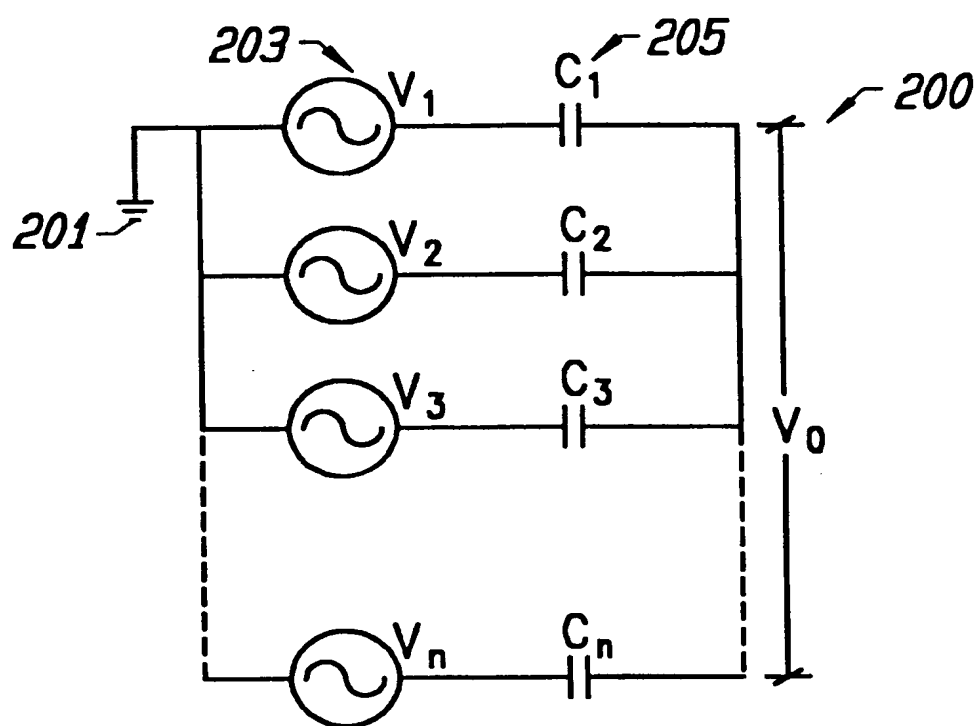


FIG. 5A

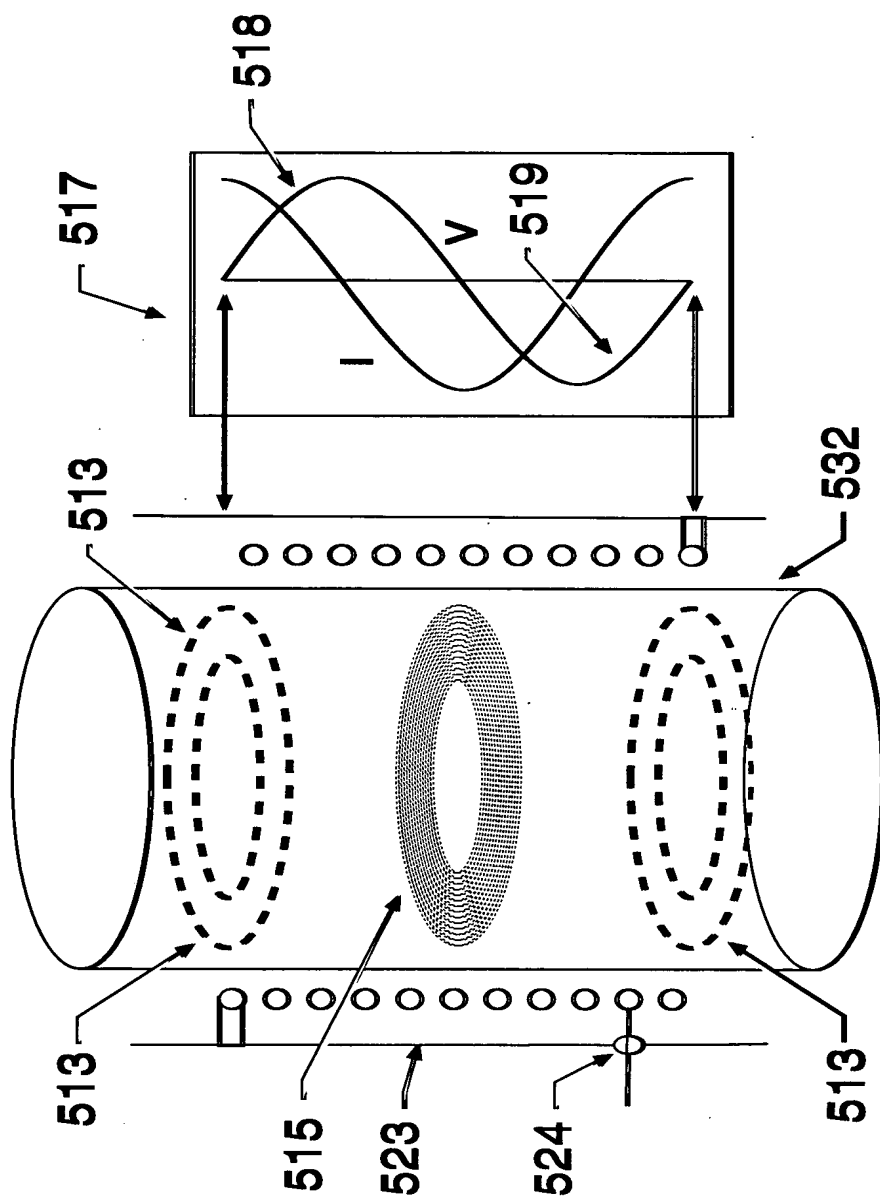


Fig. 5C

APPROVED	O.G. FIG.	
BY	CLASS	SUBCLASS
DRAFTSMAN		

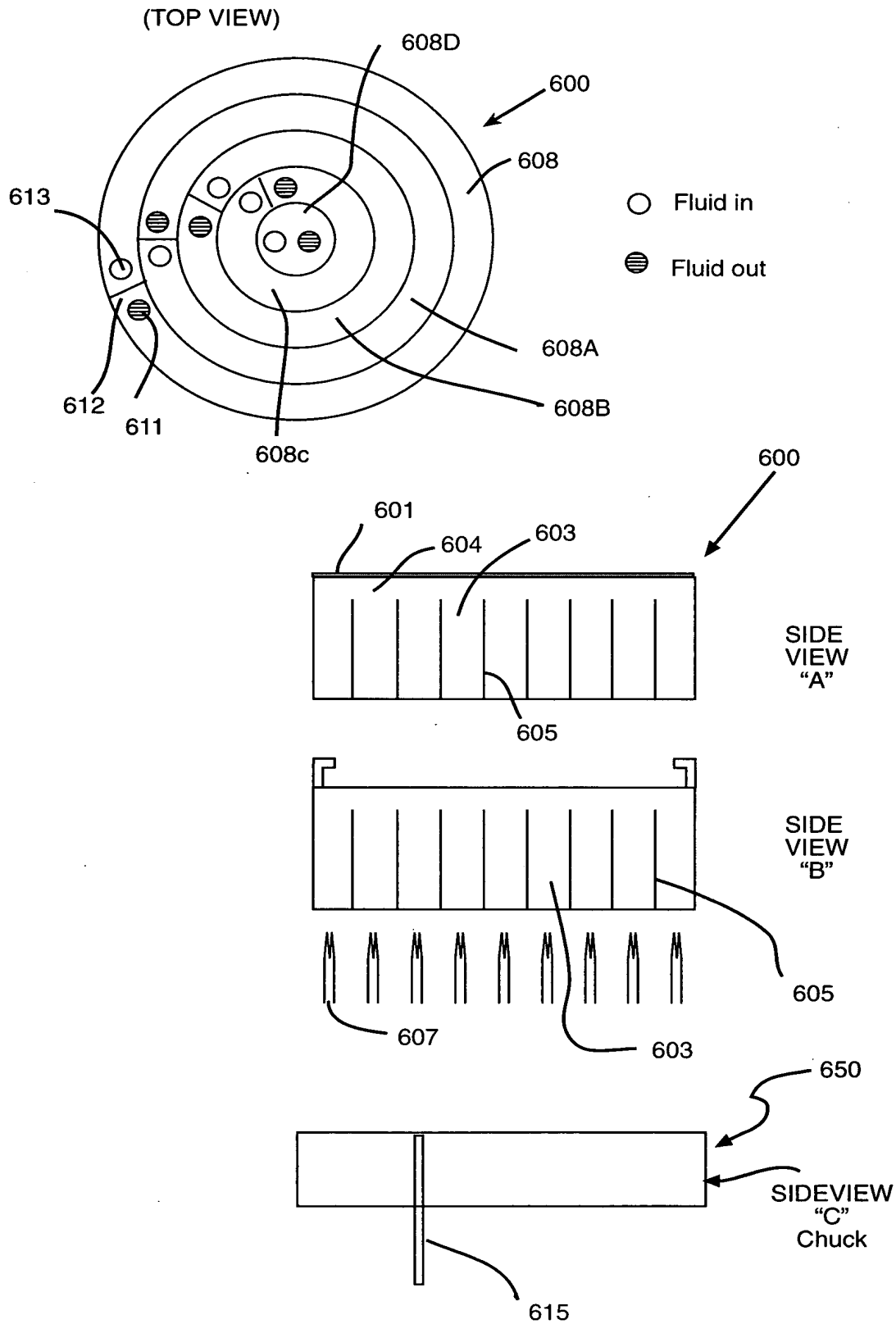


FIG. 6

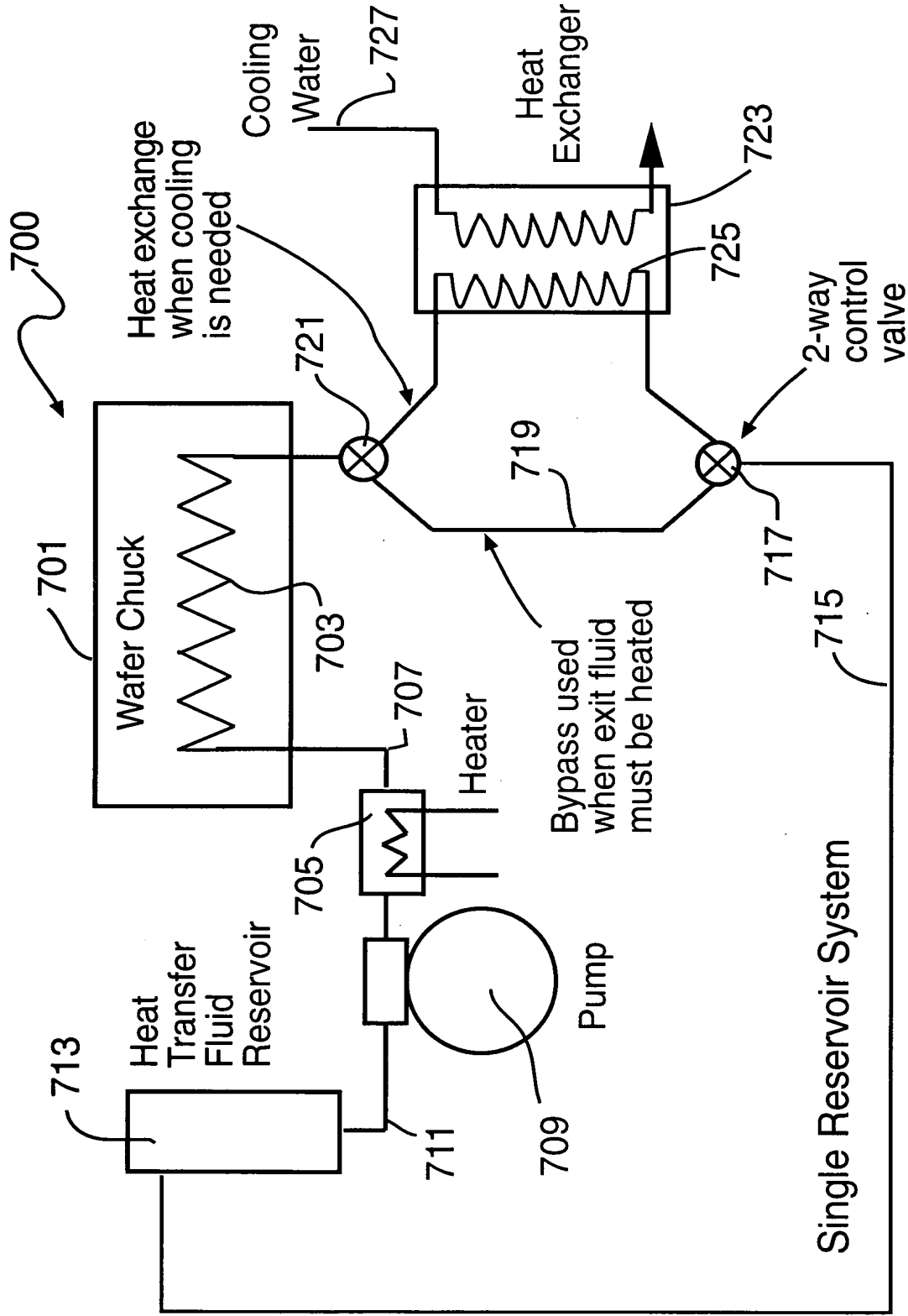


Fig. 7

APPROVED	O.G. FIG.	
BY	CLASS	SUBCLASS
DRAFTSMAN		

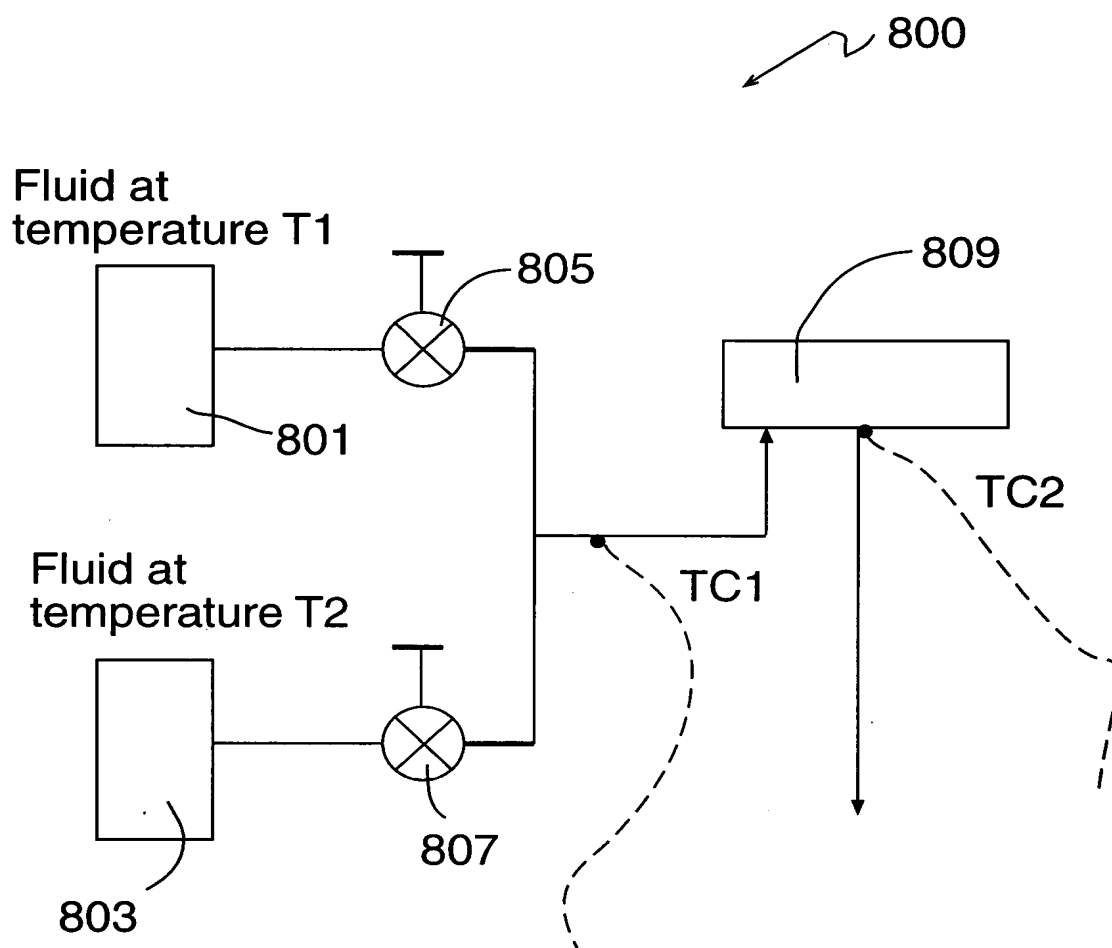


Fig. 8

APPROVED	C.G. FIG.	
BY	CLASS	SUBCLASS
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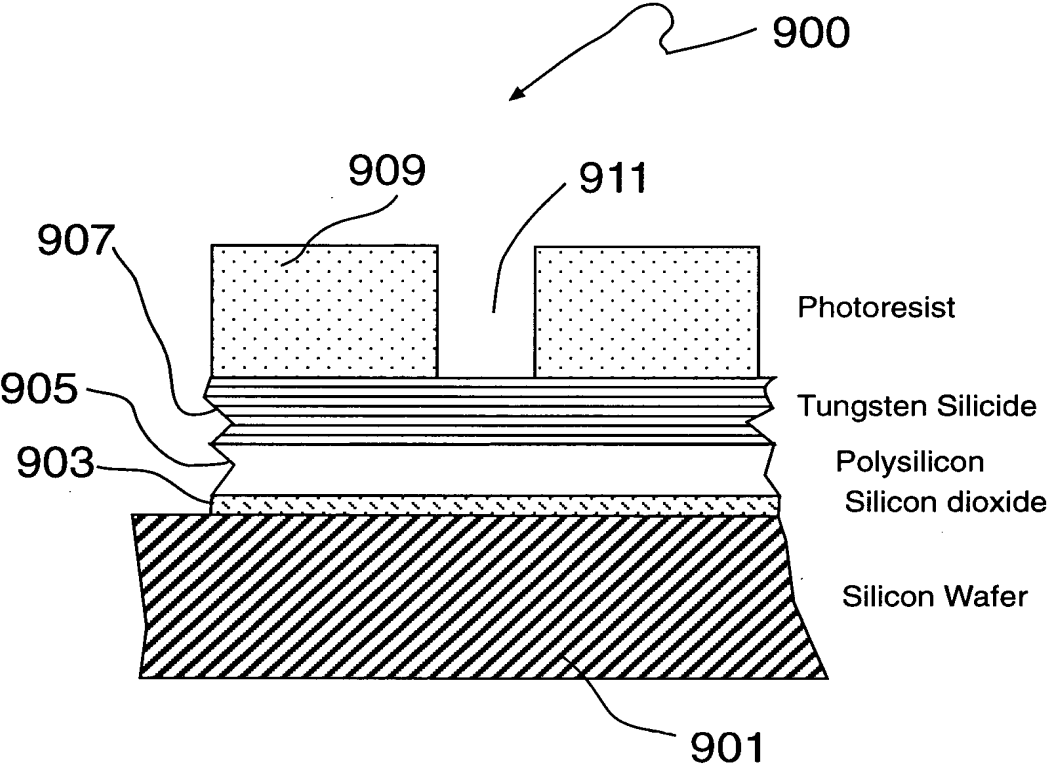
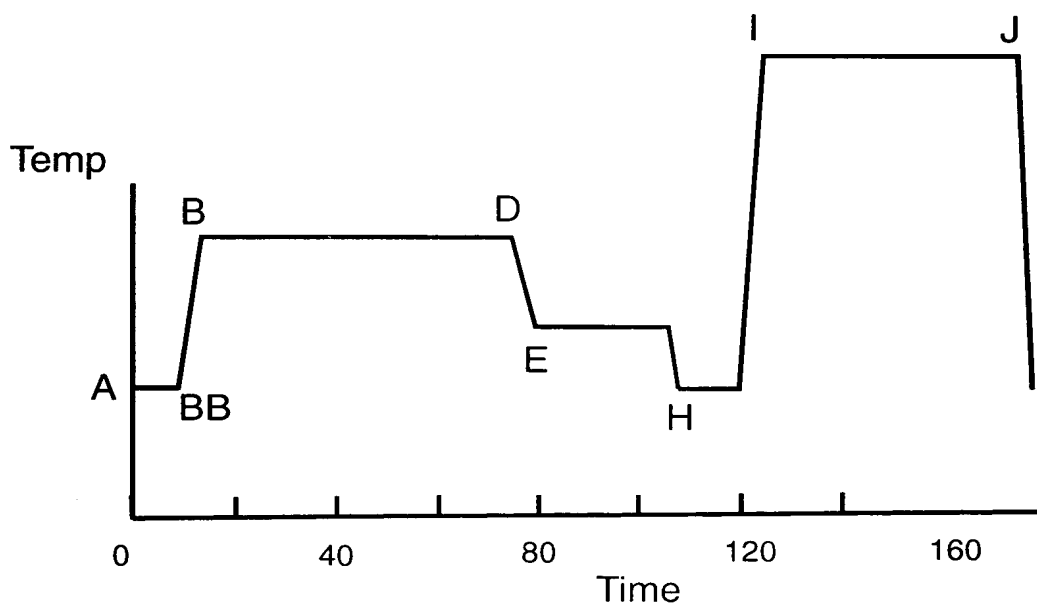
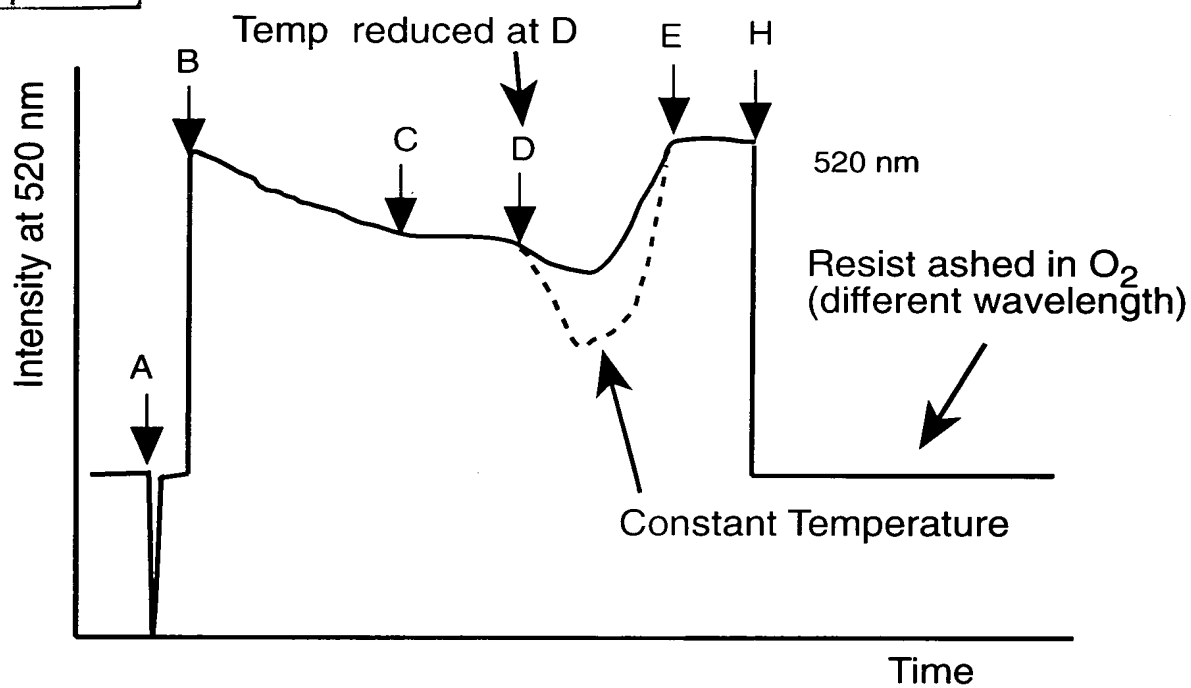


Fig. 9



A. SF₆ native oxide "breakthrough"
 B. Cl₂ plasma is ignited
 C. WSi_x begins to clear (endpoint)
 D. Polysilicon is exposed
 E. Polysilicon cleared to oxide

H. Plasma extinguished and O₂ feed gas flow is started
 I. O₂ plasma is started
 J O₂ plasma is extinguished.

Fig. 10